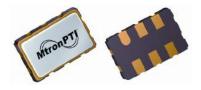






## **Electrical Specifications:**

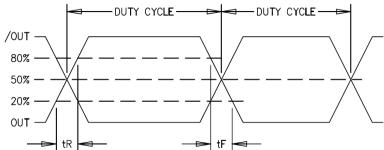
Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		100.000000		MHz	
		Free	quency Stabi	lity		
						Includes calibration
						tolerance, operating
Frequency Stability	$\Delta F/F$	-50		+50	ppm	temperature, supply
						voltage variations,
						aging and IR reflow.
			RF Output			
Output Type		LV	PECL Compatik	ole		
Output Load		50	Ω to (Vcc-2.0) \	/DC	V	
Symmetry (duty cycle)	Vон	45		55	%	Ref. 50% of waveform
Logic Level "1"	Vон	Vcc-1.025		Vcc-0.880	V	
Logic Level "0"	T <sub>DC</sub>	Vcc-1.810		Vcc-1.620	V	
Rise/Fall Time	T <sub>R</sub> /T <sub>F</sub>			0.4	ns	Ref. 20% to 80% of waveform
Start-up Time	Ts∪			10	mS	$T_{ambient} = +25^{\circ}C$
Enable Logic		70% V <sub>CC</sub> or N/C			V	Pad 1: Output Enabled
Disable Logic				30% Vcc	V	Pad 1: Output Disabled to high-Z
	S	upply Volta	ge & Power C	onsumption	n	
Operating Voltage	Vcc	3.135	3.3	3.465	V	
Supply Current	lcc			75	mA	
		Ot	ther Parameter	S		
Phase Jitter (RMS)	ΦJ			0.8	ps	12 KHz to 20 MHz







### **Output Waveform:**



# **Environmental & Packaging Requirements:**

Operating Temperature	TA	-40		+85	°C	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-S	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, 1/2 sinewave)				
Vibration		Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)				
Thermal Cycle	Per MIL-S	Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)				
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 <sup>-8</sup> atm cc/s of Helium)					
Moisture Sensitivity Level (MSL)	MSL 1					
Solderability	Per EIAJ-STD-002					
Max. Soldering Conditions	See solder profile, Figure 1					
Package Type	6-pad 3.2 X 5.0 X 1.4 mm leadless ceramic. RoHS compliant.					

## Marking, Pin Out:

Pad	Function
1	Enable/Disable
2	N/C
3	Ground
4	Output
5	Complementary Output
6	+V <sub>cc</sub>

Part Marking		
Line 1	100M000	
Line 2	M yywwvv	

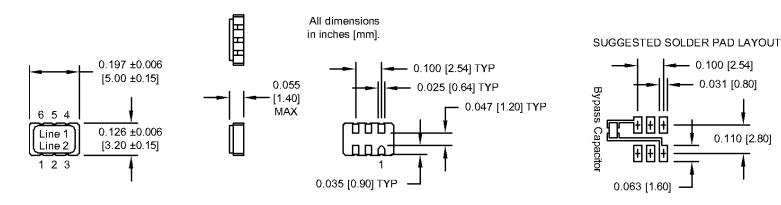
Legend		
уу	Year	
ww	Work Week	
vv	Factory Code	



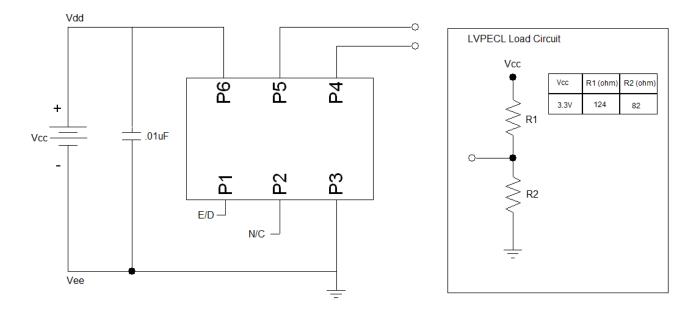




## **Dimensions:**



## **Typical Test Circuit & Load Circuit Diagrams:**



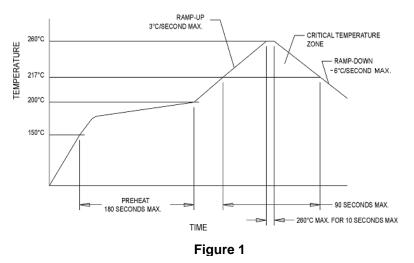
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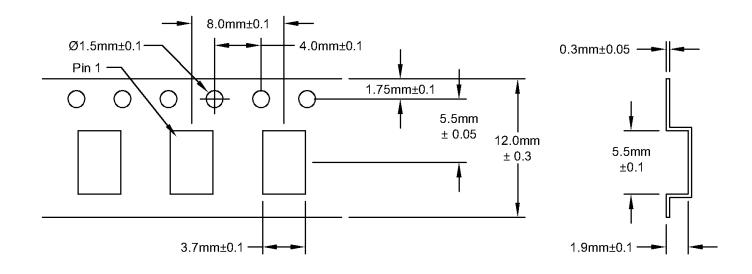




## **Soldering Conditions:**



## **Tape and Reel Specifications:**



#### **Datasheet Revision Table:**

Date	Rev.	Author	Details of Revision
02-20-20	А	BRR	Preliminary Release